

### **AMENDMENTS TO THE CLAIMS:**

The listing of claims will replace all prior versions and listings of claims in the application:

### **LISTING OF CLAIMS:**

Claim 42 (cancelled)

Claim 43 original – A process for manufacturing a resonance circuit comprising the steps of:

overlaying an electrically-conductive layer transfer sheet having a thermally transferable electrically-conductive layer on one side of a dielectric material with the thermally transferable electrically-conductive layer facing with the dielectric material surface, and then thermally transferring the thermally transferable electrically-conductive layer on the dielectric material in the predetermined pattern to form a coil-like circuit; and,

overlaying the electrically-conductive layer transfer sheet on the other side of the dielectric material with the thermally transferable electrically-conductive layer facing with the dielectric material surface, and then thermally transferring the thermally transferable electrically-conductive layer on the dielectric material in the predetermined pattern to form a condenser electrode circuit or a coil-like circuit which also serves as a condenser.